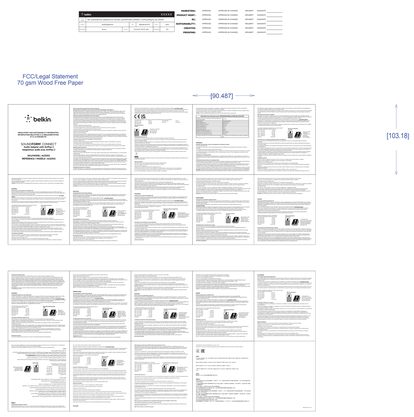
belkin

Die Line File: IDL_G3H0001-G3H0002_SAP110-111 BELKIN HEADPHONE PACKAGE

Artwork File:

REV D 00

DIE LAYOUT



Business Unit: Core

Program Manager: Andrew Camba

Packaging Engineer: Matthew Duffy

Retail Outside Dimension (Including Hang Tab)

L x W x D (in):

L x W x D (mm):

DIE/MATERIAL SPECS:

Material: Please refer to drawing

Blank Size (in): 35.476 x 62.653

Blank Size (mm): 901.088 x 1591.398

This dieline works for following skus (if any):

Unit: IN/MM

Side Shown: PRINT SIDE

Flute/Grain: horizontal

Tolerance:+/- 1/32" - 0.8mm

Drawing Scale 1:1

RELEASE DATE: 07/08/2020

DIELINE:

Intermediate

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PRINT SPECS:

Color Plates:

Finish:

Notes:

DO NOT PRINT
DIE LINES, PRINTERS NOTES